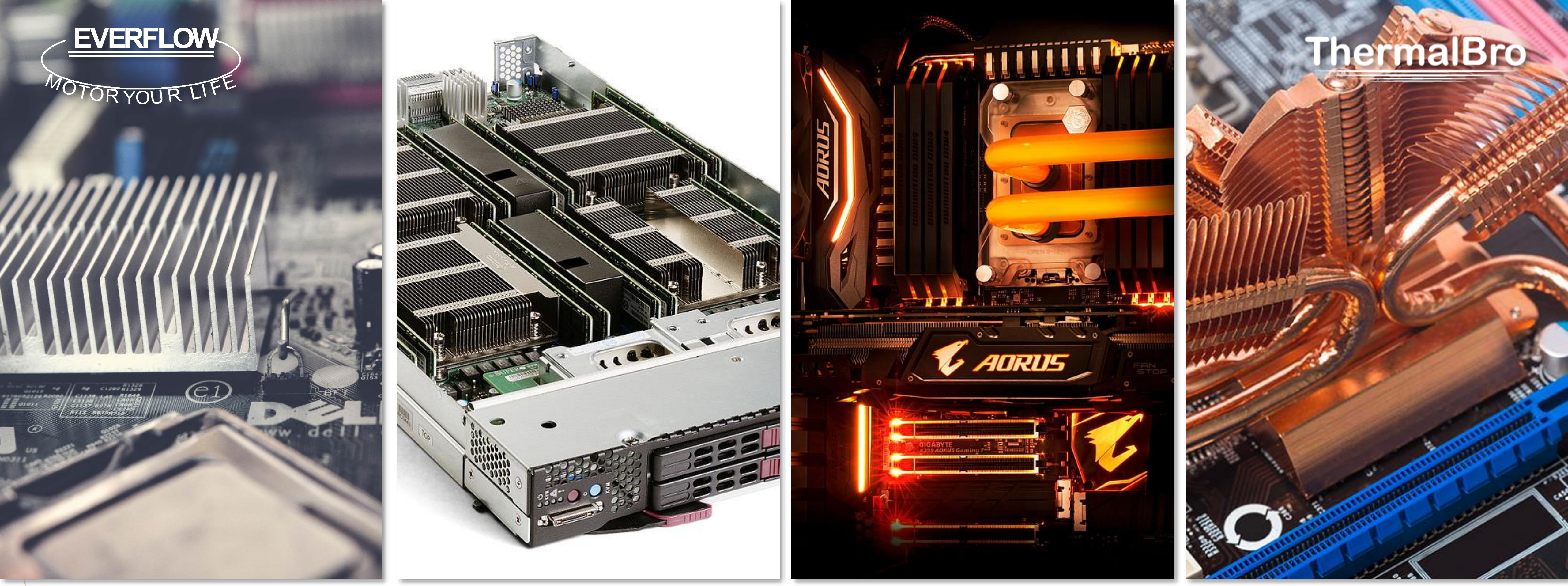

EVERFLOW Thermal Solution

Product catalog

EVERFLOW TECHNOLOGY CO.,LTD.

Product Catalog

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P4:2U-passive,300W，118*78*64.3	P14:2U-passive,205W，108*78*64	**LGA 1150/1151/1200**
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P8:4U-active,350W，118*143*135	P18:4U-active,205W，108*92*120	P26:1U-passive,95W，90*90*26
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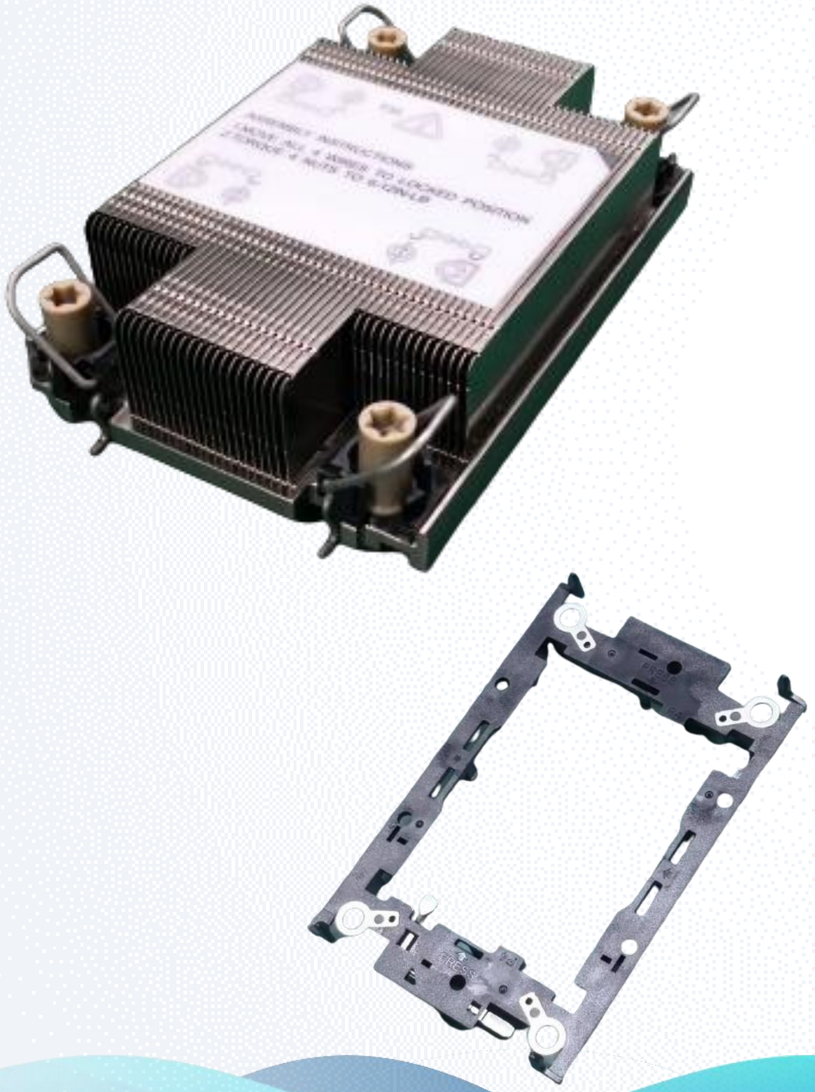
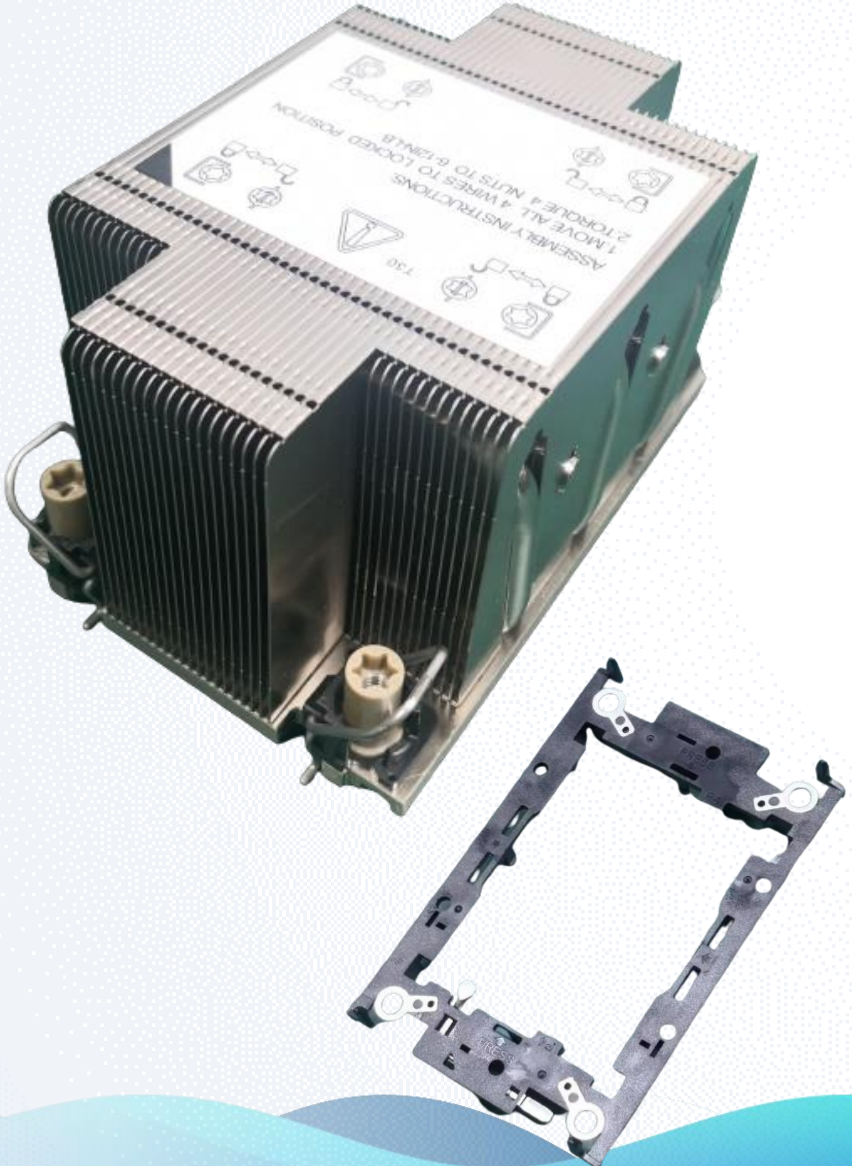
	P22:4U-active,160W，93*95*119	**SP6**
		P31:4U-active,350W，118.2*92.5*125.4
		Custom radiator module： P31~P37

Intel LGA 4677



Model No	EA7190
Features	Precision stamping buckle FIN processing technology. High-density aluminum heat dissipation fins to increase the heat dissipation area; Intel special screw installation, convenient, stable and reliable. **Applied to 1U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP205W** (requires the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN Product size: 118x78x25.3mm Product weight: 236g Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4677



Model No	EA7290
Features	Precision stamping buckle FIN processing technology; 5 heat pipes are added to the copper base plate to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Intel special screw installation, convenient, stable and reliable; **Applied to 2U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP300W** (requires the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN + 5 high-efficiency heat pipes Product size: 118x78x64.3mm Product weight: 429g Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

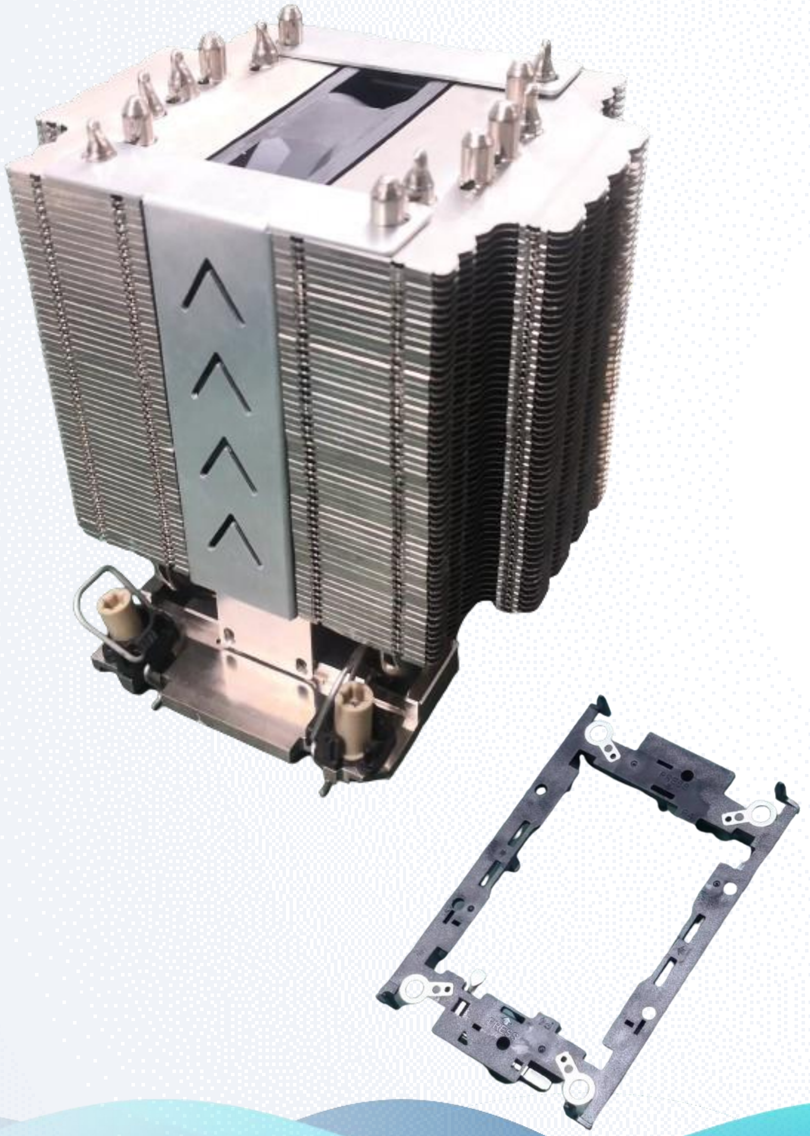
Intel LGA 4677

Model No	EA7291
Features	Five high-efficiency U-shaped heat pipes, with direct contact of high-efficiency heat pipes at the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Intel special screw installation, convenient, stable and reliable; **Applied to 2U active solutions.**
Technical parameters	Applicable power consumption: **TDP 300W** Product weight: 510g Heat dissipator: copper bottom + aluminum FIN + 5 high-efficiency heat pipes Product size: 113x80x66.3mm Fan speed: PWM1500-9300 rpm Noise: 54dBA Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4677

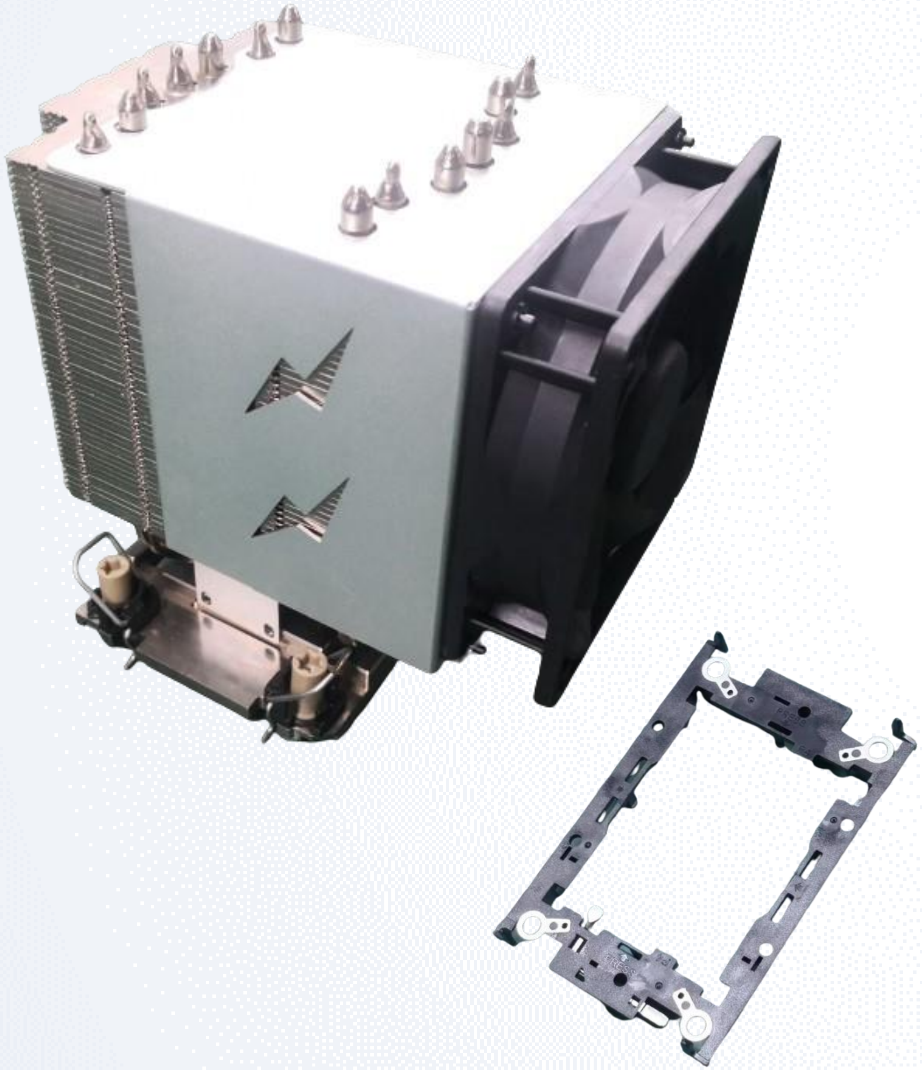
Model No	EA7491
Features	Six high-efficiency U-shaped heat pipes with pure copper plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Intel special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 300W** Product weight: 773g Heat dissipator: copper bottom + aluminum FIN + 6 high-efficiency heat pipes Product size: 116.7x92.5x125mm Fan speed: PWM1300-3500 rpm Noise: 21-45dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4677



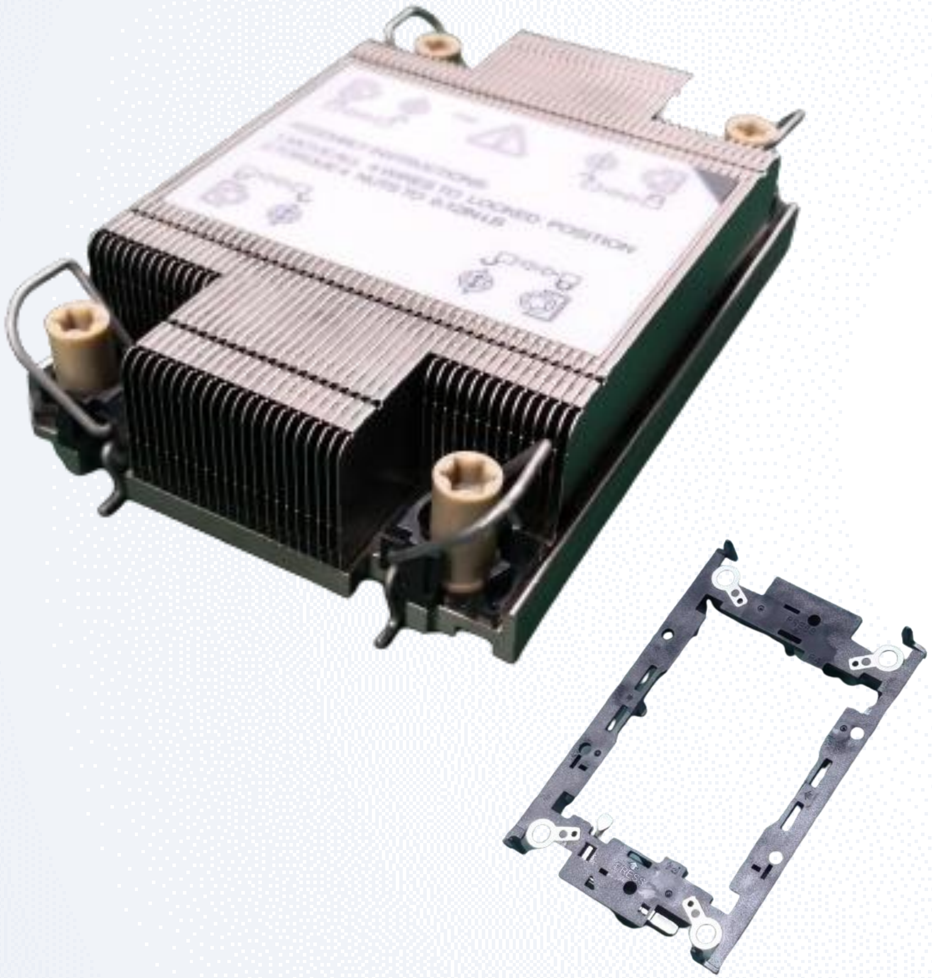
Model No	EA7492
Features:	Seven high-performance U-shaped heat pipes, soldered with pure copper plates at the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Intel special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 350W** Product weight: 790g Heat dissipator: copper bottom + aluminum FIN + 6 high-efficiency heat pipes Product size: 118x118x135mm Fan speed: PWM1300-3500 rpm Noise: 21-45dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4677



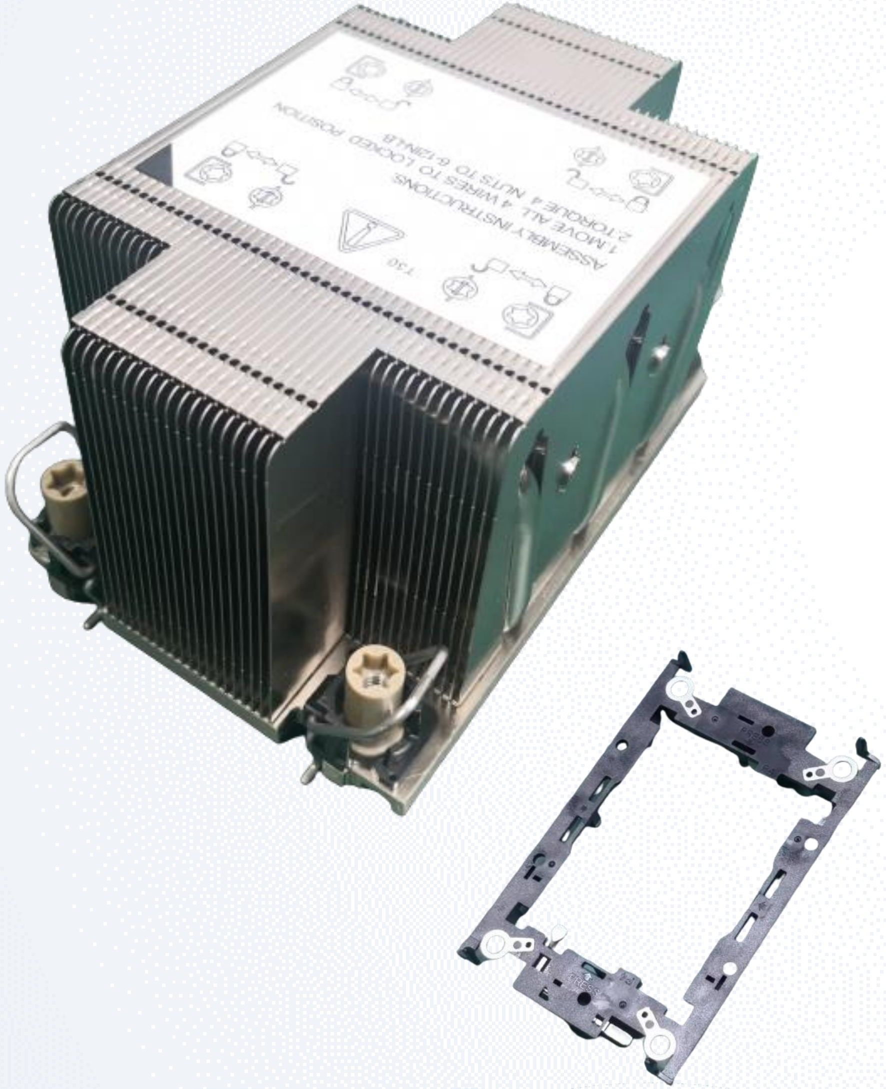
Model No	EA7493
Features	7 high-efficiency U-shaped heat pipes, soldered with pure copper plate at the bottom; Adopt precision stamping buckle FIN processing technology, High density, increase heat dissipation area; Adopt dual temperature control ball and double fan, stable performance and long life; Intel special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 350W** Product weight: 925g Heat dissipator: copper bottom + aluminum FIN + 6 high-efficiency heat pipes Product size: 118x143x135mm Fan speed: PWM1300-3500 rpm Noise: 21-45dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4189



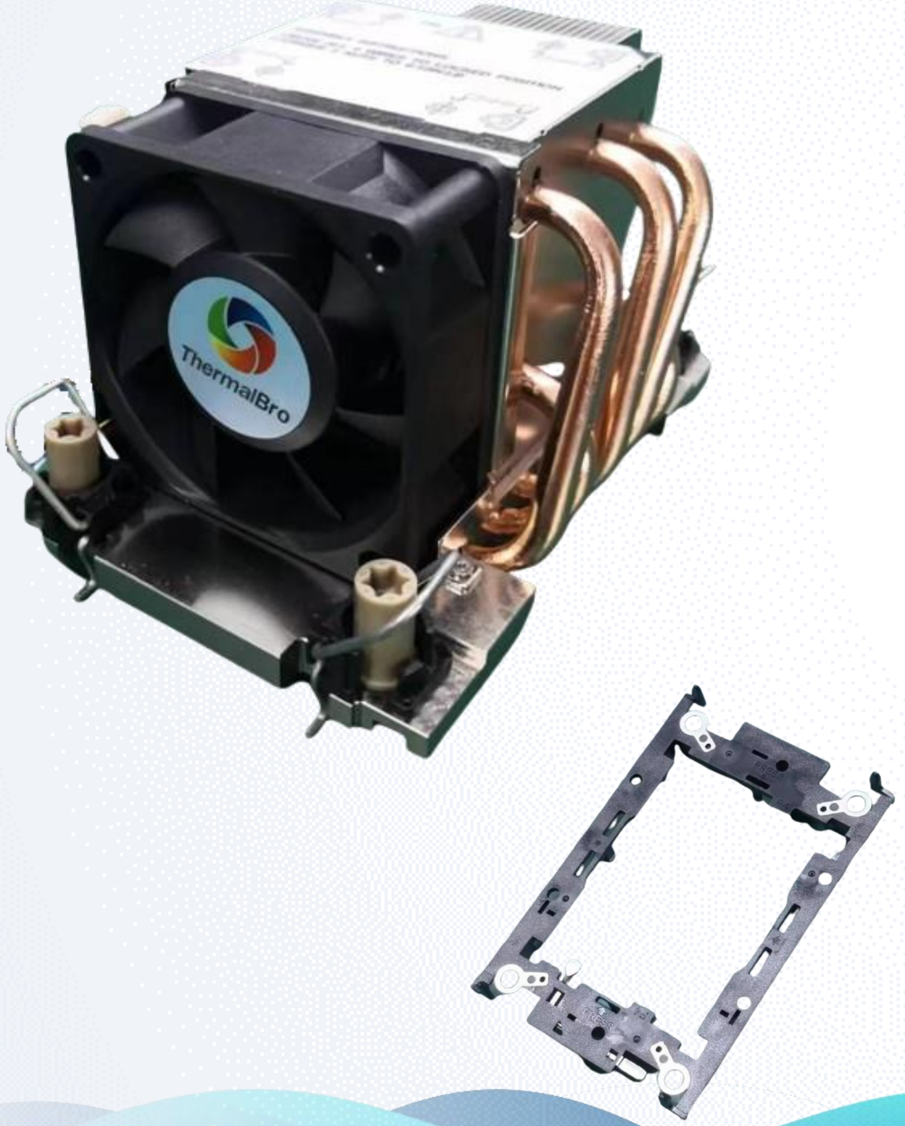
Model No	EA7170
Features	Precision stamping buckle FIN processing technology; High-density aluminum heat dissipation fins to increase the heat dissipation area; Intel special screw installation, convenient, stable and reliable; **Applied to 1U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP205W** (requires the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN Product size: 113x78x25.3mm Product weight: 234g Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4189



Model No	EA7270
Features	Precision stamping buckle FIN processing technology; 5 heat pipes are added to the copper base plate to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the Heat dissipation area; Intel special screw installation, convenient, stable and reliable; **Applied to 2U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP280W** (with the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN + 5 high-efficiency heat pipes Product size: 113x78x64.3mm Product weight: 401g Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4189



Model No	EA7271
Features	Five high-efficiency U-shaped heat pipes, with direct contact of high-efficiency heat pipes at the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Intel special screw installation, convenient, stable and reliable; **Applied to 2U active solutions.**
Technical parameters	Applicable power consumption: **TDP 280W** Product weight: 510g Heat dissipator: copper bottom + aluminum FIN + 5 high-efficiency heat pipes Product size: 113x80x66.3mm Fan speed: PWM1500-9300 rpm Noise: 54dBA Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 4189

Model No	**EA7471**
Features	Six high-efficiency U-shaped heat pipes with pure copper plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Intel special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 280W** Product weight: 767g Heat dissipator: copper bottom + aluminum FIN + 6 high-efficiency heat pipes Product size: 116.7x92.5x125mm Fan speed: PWM1300-3500 rpm Noise: 21-45dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 3647

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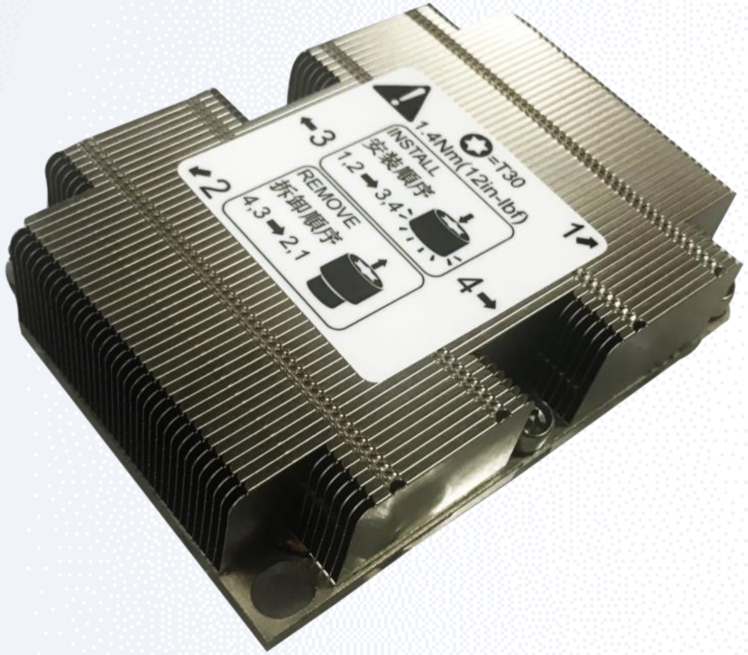

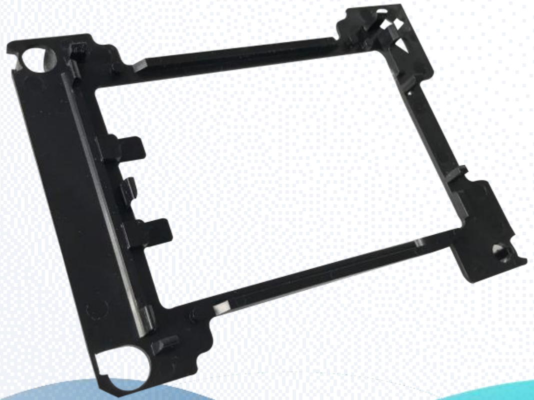

Model No	**EA7150**
Features	Precision stamping buckle FIN processing technology; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; **Applied to 1U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP145W** (with the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN Product size: 108x78x26.0mm Product weight: 360g Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

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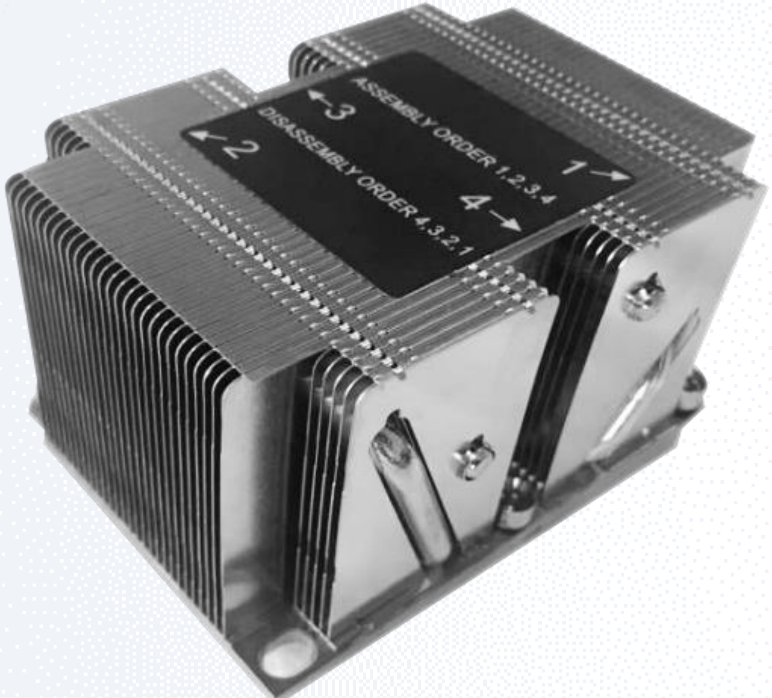
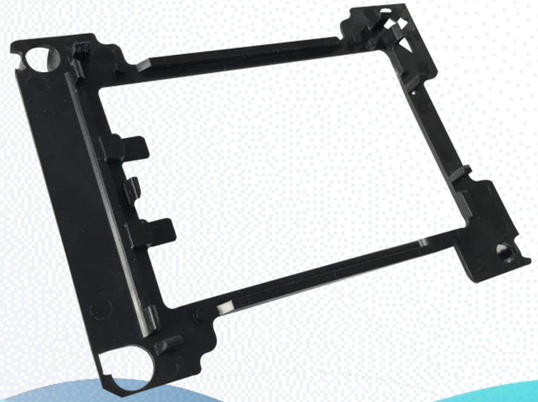
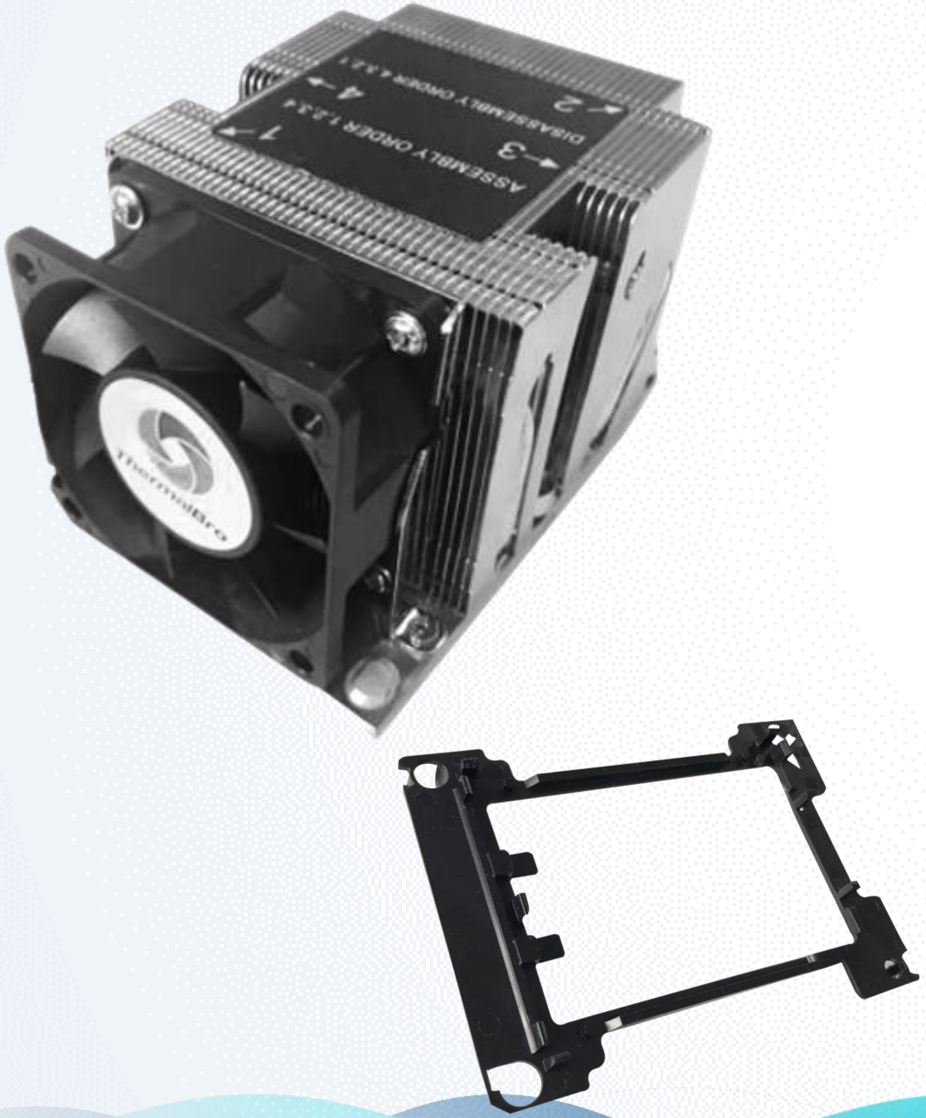
Intel LGA 3647





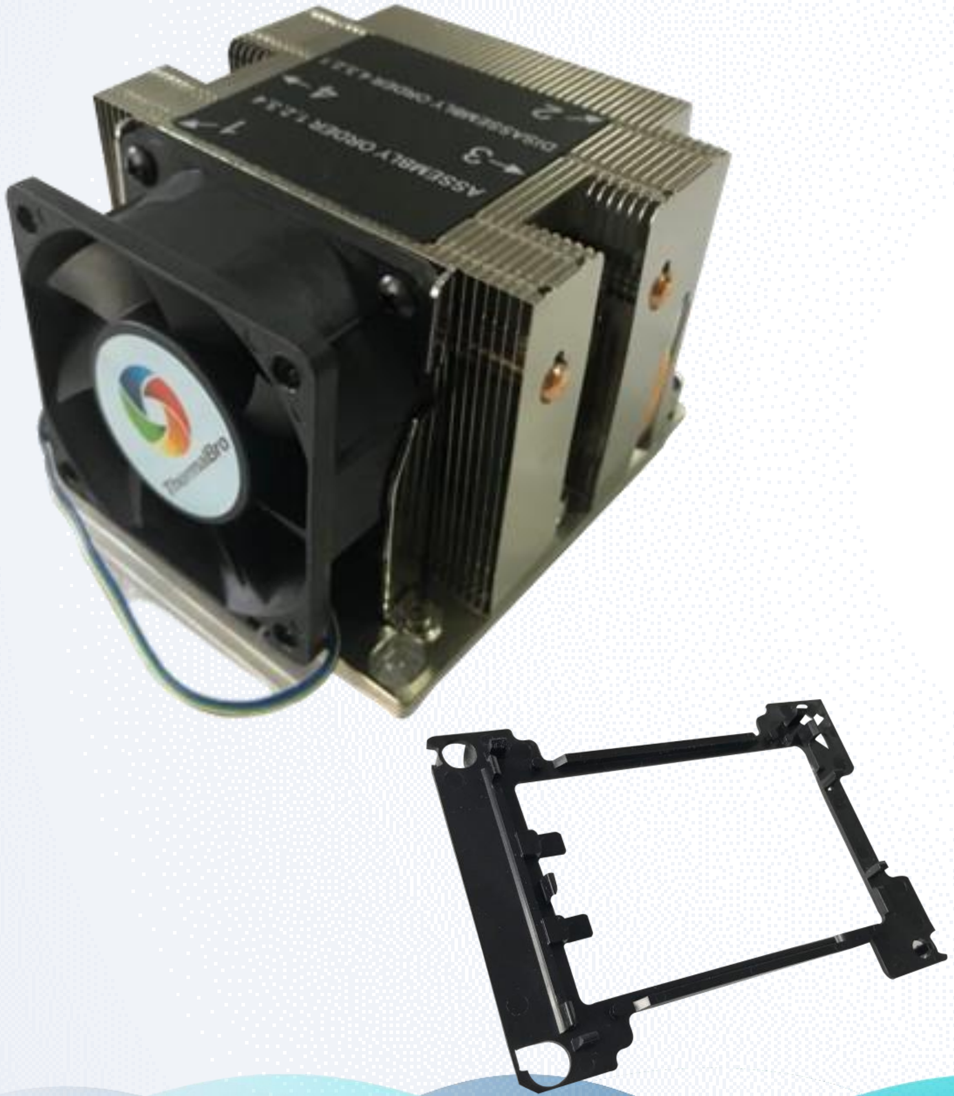
Model No	EA7250
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with 4 heat pipes to improve The thermal conduction efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; **Applied to 2U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP205W** (requires the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN + 4 high-efficiency heat pipes Product size: 108x78x64.0mm Product weight: 415g Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 3647



Model No	EA7251
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with 4 heat pipes to improve the thermal conduction efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; **Applied to 2U active solutions.**
Technical parameters	Applicable power consumption: **TDP 205W** Product weight: 455g Heat dissipator: copper bottom + aluminum FIN + 4 high-efficiency heat pipes Product size: 108x78x65mm Fan speed: PWM2500-6800 rpm Noise: 21-44dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 3647



Model No	**EA7252**
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with 4 heat pipes to improve the thermal conduction efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; **Applied to 2U active solutions.**
Technical parameters	Applicable power consumption: **TDP 205W** Product weight: 398g Heat dissipator: copper bottom + aluminum FIN + 4 high-efficiency heat pipes Product size: 97x88x65mm Fan speed: PWM2500-6800 rpm Noise: 21-44dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

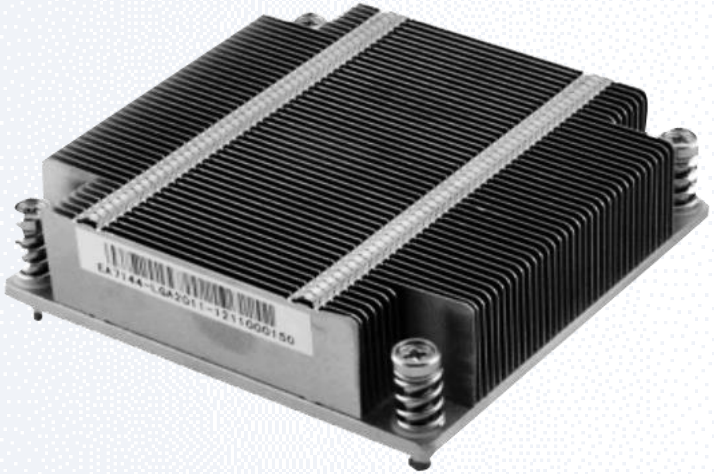
Intel LGA 3647

Model No	**EA7451**
Features	Four high-efficiency U-shaped heat pipes with pure copper plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 205W** Product weight: 565g Heat dissipator: copper bottom + aluminum FIN + 4 high-efficiency heat pipes Product size: 118x92.5x128mm Fan speed: PWM1300-3500 rpm Noise: 23-43dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 3647

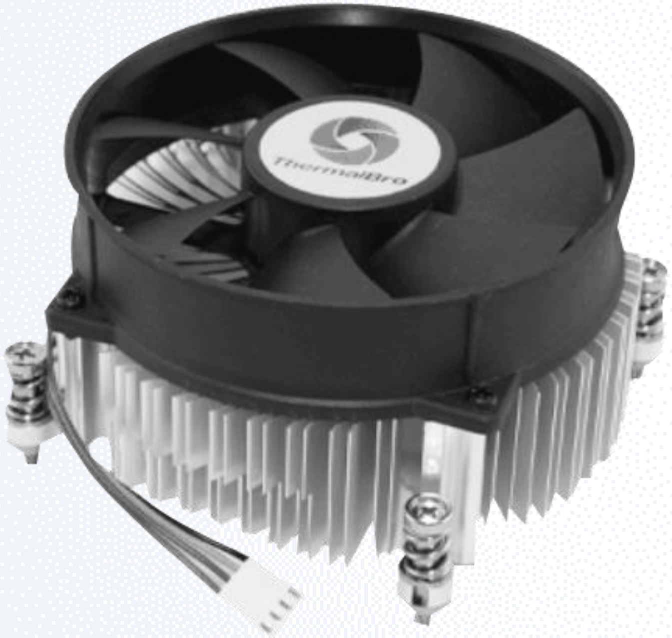
Model No	EA7452
Features	Precision stamping, heat pipe through FIN processing technology; 6 heat pipes are added to the copper base plate to improve the thermal conduction efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 205W** Product weight: 820g Heat dissipator: copper bottom + aluminum FIN + 6 high-efficiency heat pipes Product size: 108x92x120mm Fan speed: PWM1300-3500 rpm Noise: 23-43dB Thermal paste: 7762 Accessories: CPU protective plastic bracket (optional)

Intel LGA 2011



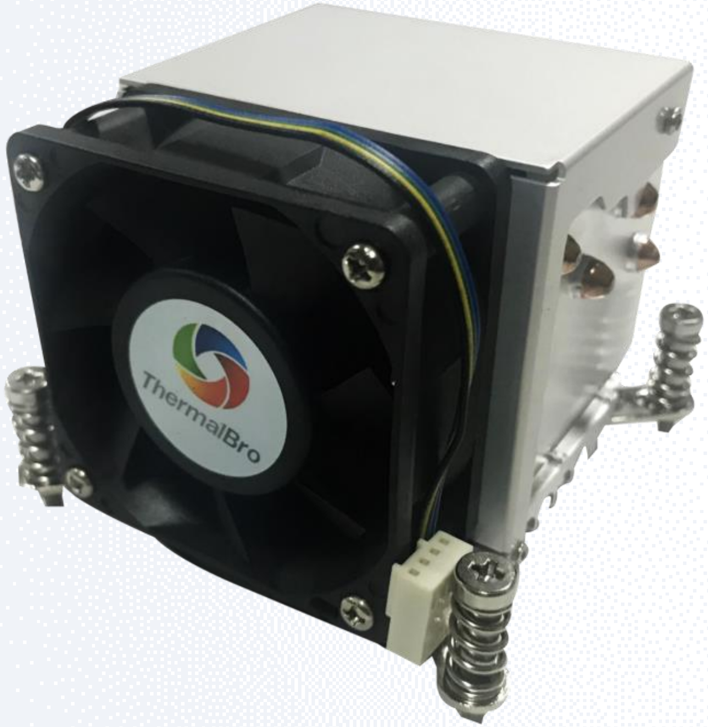
Model No	EA7144
Features	Precision stamping buckle FIN processing technology; High-density heat dissipation fins to increase the heat dissipation area ; Spring screw installation, convenient, stable and reliable; **Applied to 1U passive-style solutions.**
Technical parameters	Scope of application: **TDP95W** (with the cooperation of the air duct of the chassis system) Heat dissipator: copper bottom + aluminum FIN Product size: 90x90x27mm Product weight: 237 g Thermal paste: 7762

Intel LGA 2011



Model No	EA7241
Features	Aluminum extrusion sunflower process is adopted; High-density heat dissipation fins to increase the heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance; Spring screw installation, convenient, stable and reliable; **Applies to 2U active solutions**
Technical parameters	Applicable power consumption: **TDP 95W** Product weight: 350g Diffuser: high multiplier aluminum extrusion Product size: Φ102.5x61.5mm Fan speed: PWM800-3500 rpm Noise: 21-44dB Attachment: 1g sachet of thermal paste

Intel LGA 2011



Model No	EA7243
Features	4 high-efficiency heat pipes in direct contact with the CPU; Adopt FIN wearing process, high-density aluminum FIN to increase the heat dissipation area; Temperature-controlled 2ball bearing fan, stable performance and long life; Spring screw installation, convenient, stable and reliable; **Applied to 2U active solutions.**
Technical parameters	Applicable power consumption: **TDP 130W** Product weight: 305g Heat dissipator: copper bottom + aluminum FIN + 4 high-efficiency heat pipes Product size: 90x90x65mm Fan speed: PWM2500-5500 rpm Noise: 21-44dB Thermal paste: 7762

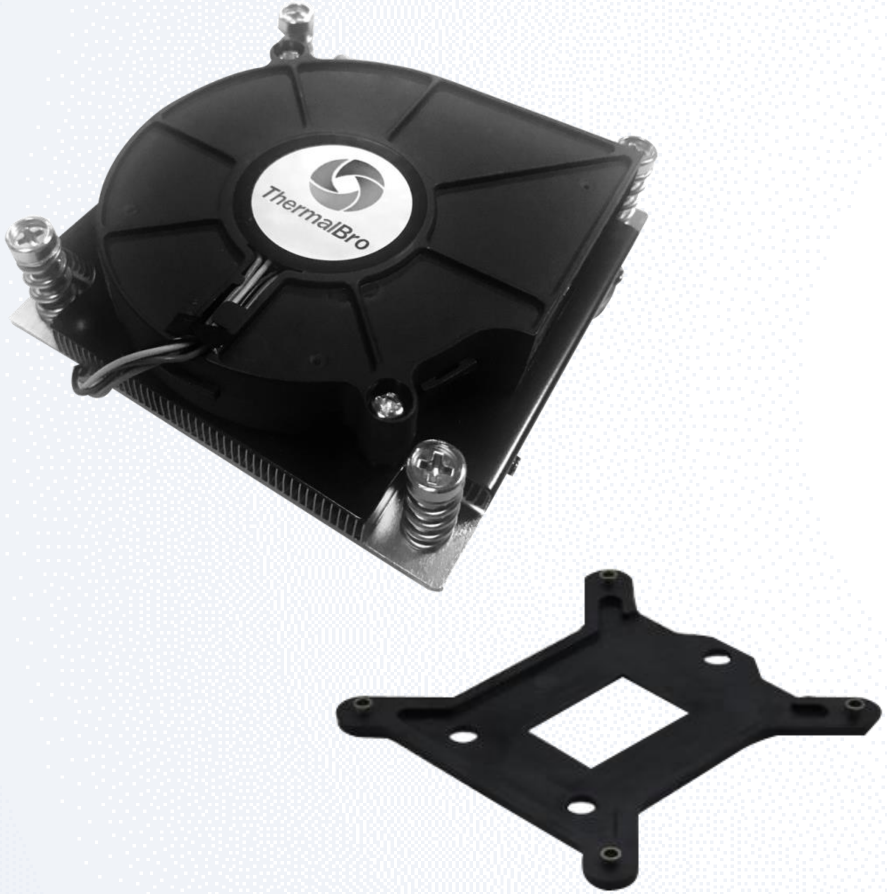
Intel LGA 1700

Model No	EA7432
Features	Five high-efficiency U-shaped heat pipes, with a pure copper base plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, Increase the heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special spring screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 200W** Product weight: 515g Heat dissipator: copper bottom + aluminum FIN + 5 high-efficiency heat pipes Product size: 93x95x119mm Fan speed: PWM1300-3500 rpm Noise: 23-43dB Thermal paste: 7762

Intel LGA 2066

Model No	EA7442
Features	Five high-efficiency U-shaped heat pipes, with a pure copper base plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, Increase the heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special spring screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 200W** Product weight: 515g Heat dissipator: copper bottom + aluminum FIN + 5 high-efficiency heat pipes Product size: 93x95x119mm Fan speed: PWM1300-3500 rpm Noise: 23-43dB Thermal paste: 7762

Intel LGA 1150/1151/1200



Model No	EA7121
Features	All-copper integrated shovel FIN processing technology to improve thermal conductivity efficiency; High-density heat dissipation fins to increase the heat dissipation area; Temperature-controlled ball turbine fan, stable performance and long life; Spring screw installation, convenient, stable and reliable; **Applied to 1U active solutions.**
Technical parameters	Applicable power consumption: **TDP 95W** Product weight: 406g Heat dissipator: Pure copper material (Cu1100) Product size: 90x88.3x27mm Fan speed: PWM2000-5500 rpm Noise: 23-43dB Accessories: 1g bag of thermal paste + 1 plastic backplate

Intel LGA 1150/1151/1200

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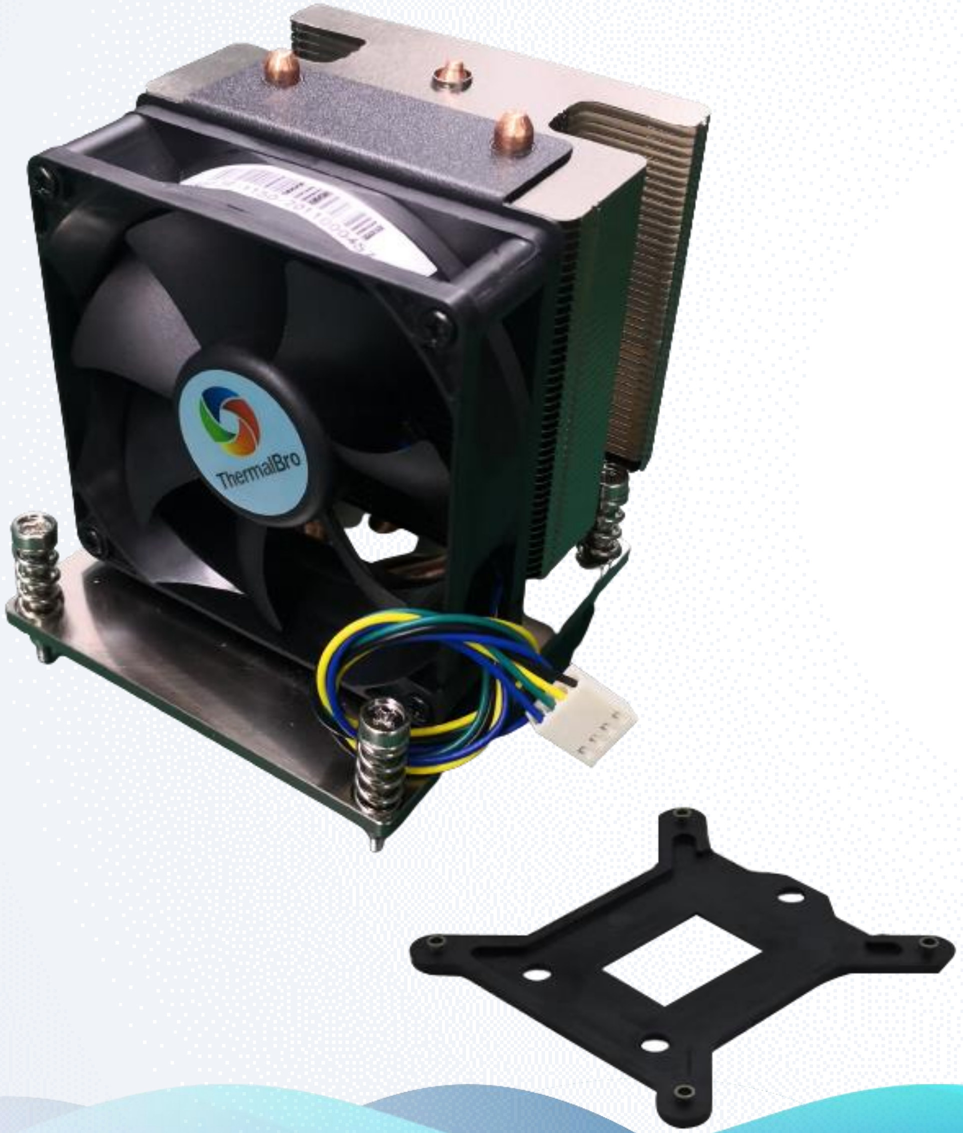
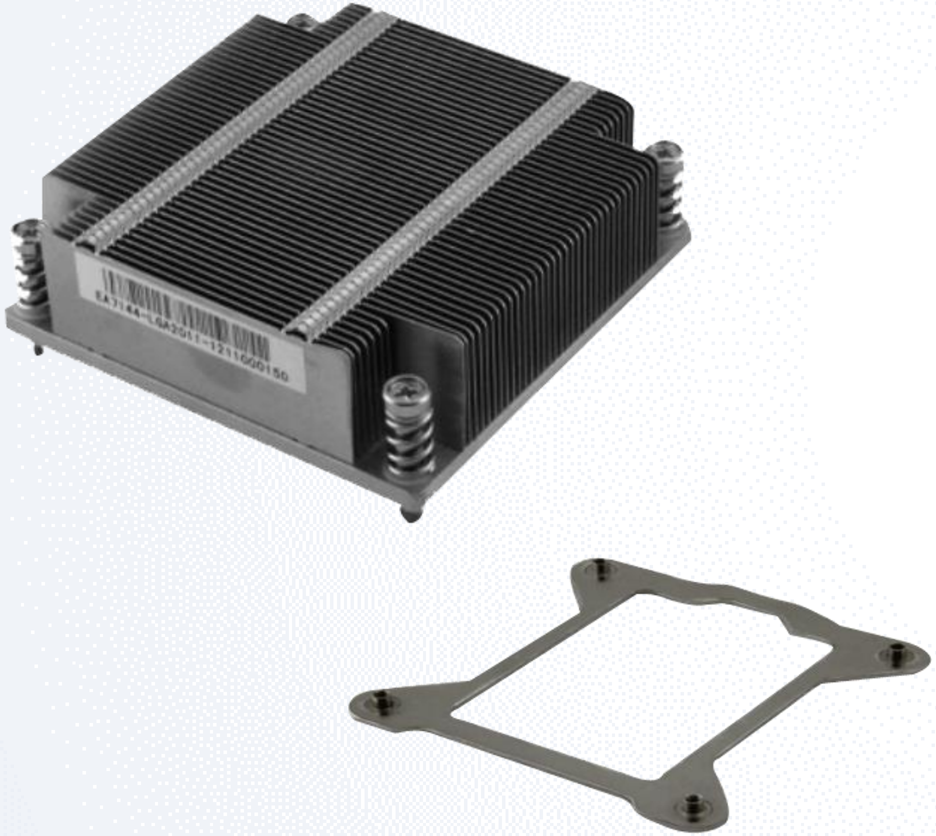


Model No	EA6139
Features	Precision stamping buckle FIN processing technology; 3 heat pipes are added to the copper base plate to improve the thermal conductivity efficiency; High-density heat dissipation fins to increase the heat Dissipation area; Special screw installation, convenient, stable and reliable; **Applied to 3U active solutions.**
Technical parameters	Applicable power consumption: **TDP 95W** Product weight: 450g Heat dissipator: copper bottom + aluminum FIN+3 heat pipe Product size: 94.5x85x94mm Fan speed: PWM2000-4000 rpm Noise: 22-35.5dB Accessories: 1g bag of thermal paste + 1 plastic backplate

Intel LGA 1150/1151/1156

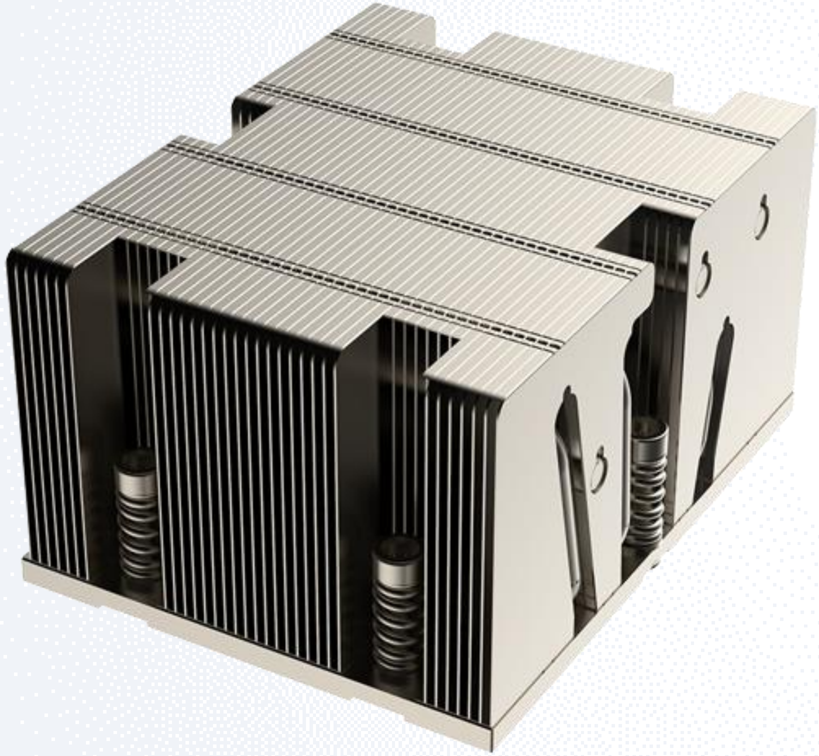


Model No	EA7127
Features	Precision stamping buckle FIN processing technology; High-density heat dissipation fins to increase the heat Dissipation area; Spring screw installation, convenient, stable and reliable; **Applied to 1U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP 95W** (with the cooperation of the air duct of the chassis system) Product weight: 237g Heat dissipator: copper bottom + aluminum FIN Product size: 90x90x26mm Accessories: 1g bag of thermal paste + 1 plastic backplate

AMD SP5

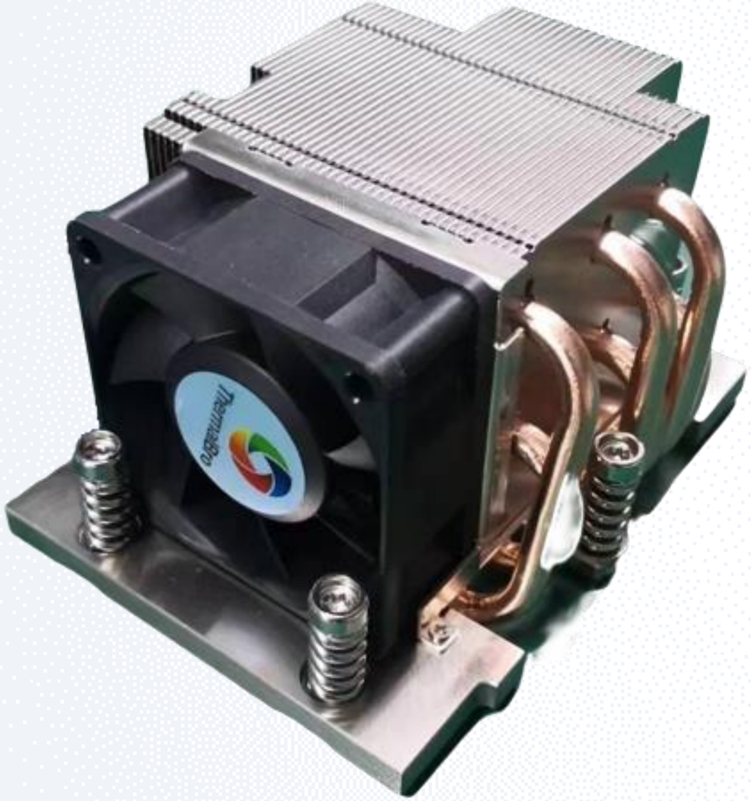
Model No	EA71A0
Features	Precision stamping buckle FIN processing technology; High-density aluminum heat dissipation fins to increase the heat dissipation area; AMD's special screw installation is convenient, stable and reliable; **Applied to 1U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP260W** (requires the cooperation of the air duct of the chassis system) Product weight: 315g Heat dissipator: copper bottom + aluminum FIN Product size: 118x92.4x25.0mm Thermal paste: 7762

AMD SP5



Model No	EA72A0
Features	Precision stamping buckle FIN processing technology; The copper base plate is welded with 6 heat pipes to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; AMD's special screw installation is convenient, stable and reliable; **Applied to 2U passive-style solutions.**
Technical parameters	Applicable power consumption: **TDP320W** (with the cooperation of the air duct of the chassis system) Product weight: 547g Heat dissipator: copper bottom + aluminum FIN + 6 high-efficiency heat pipes Product size: 118x92.4x64.5mm Thermal paste: 7762

AMD SP5



Model No	EA72A1
Features	6 high-efficiency U-shaped heat pipes, soldered with pure copper plate at the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special screw installation, convenient, stable and reliable; **Applied to 2U active solutions.**
Technical parameters	Applicable power consumption: **TDP 320W** Product weight: 548g Heat dissipator: copper bottom + aluminum FIN+6 heat pipe Product size: 118x92.5x64.5mm Fan speed: PWM1500-9300 rpm Noise: 54dBA Thermal paste: 7762

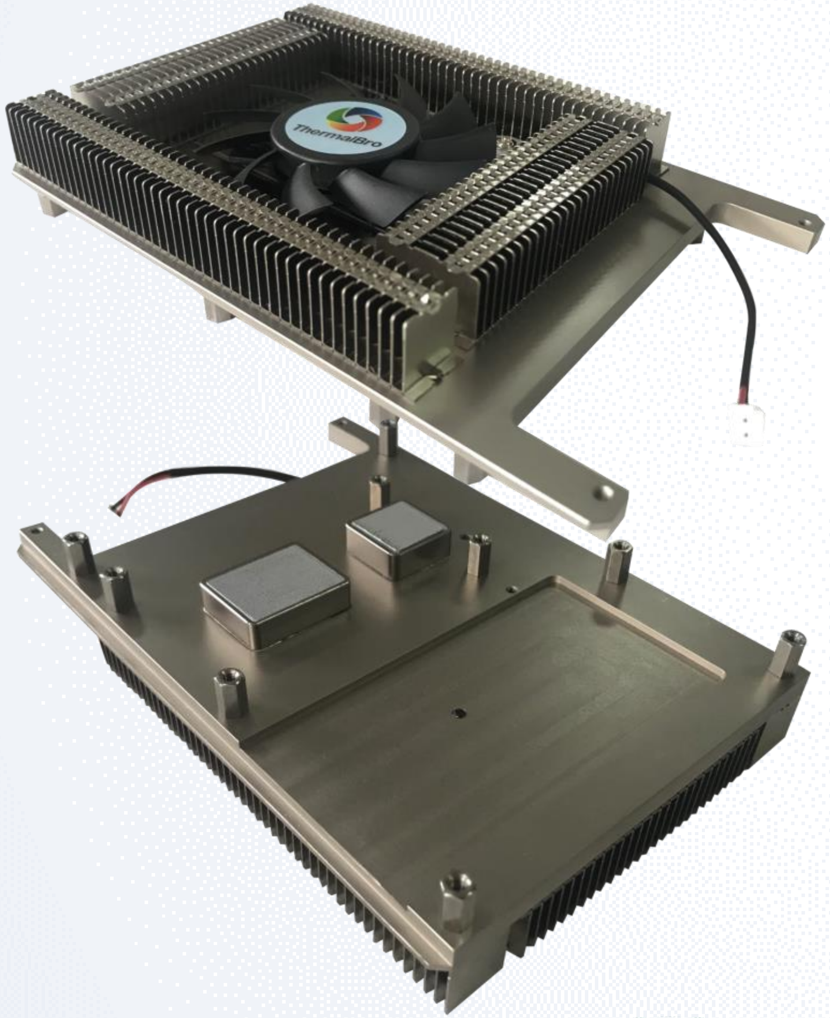
AMD SP5

Model No	**EA74A1**
Features	Six high-efficiency U-shaped heat pipes with pure copper plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 350W** Product weight: 830g Heat dissipator: copper bottom + aluminum FIN+6 heat pipe Product size: 118x92.4x125.5mm Fan speed: PWM1500-4500 rpm Noise: 22-48.5dB Thermal paste: 7762

AMD SP6

Model No	EA74B1
Features	Six high-efficiency U-shaped heat pipes with pure copper plate welded to the bottom; Adopt precision stamping buckle FIN processing technology, high density, increase heat dissipation area; Temperature-controlled 2Ball bearing Fan, stable performance and long life; Special screw installation, convenient, stable and reliable; **Applied to 4U active solutions.**
Technical parameters	Applicable power consumption: **TDP 350W** Product weight: 774g Heat dissipator: copper bottom + aluminum FIN+6 heat pipe Product size: 118.2x92.5x125.4mm Fan speed: PWM1500-4500 rpm Noise: 22-48.5dB Thermal paste: 7762

Cooler



Model No	Custom Cooler
Features	Precision stamping buckle FIN processing technology; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; Active solutions for professional boards.
Technical parameters	Applicable power consumption: customer-owned board chip **(TDP 65W)** Heat dissipator: aluminum plate + aluminum FIN Material: AL6063+AL1050 Product weight: 510g Product size: 118x80x66.3mm Service life: >70000h

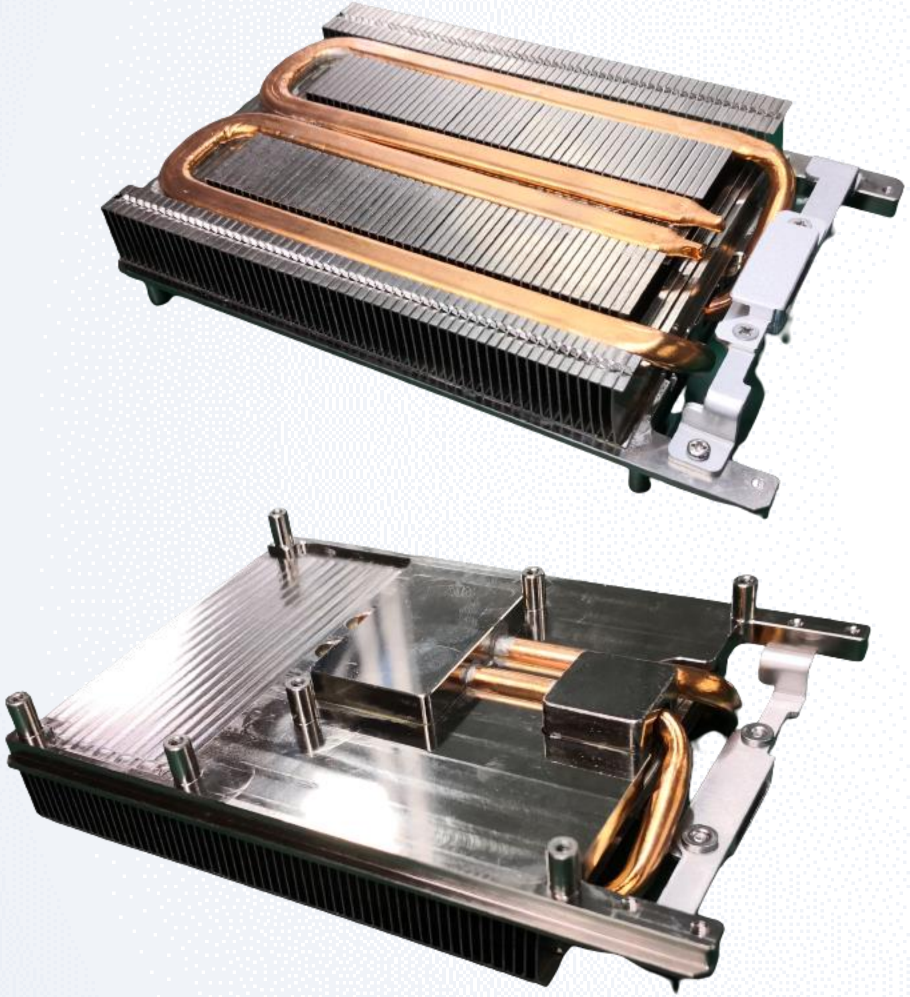
Cooler

Model No	Custom Cooler
Features	Aluminum extrusion processing technology is adopted; The surface anode is black, and the heat dissipation performance is stable; Spring screw installation, easy and reliable installation; It is used in low-power board chip cooling solutions.
Technical parameters	Scope of application: Customer-owned board chip **(TDP 35W)** Heat dissipator: Aluminum extruded AL6063 machined anode black Product size: 73x54x25.5mm Weight: 70g Service life: more than 50000 hours

Cooler

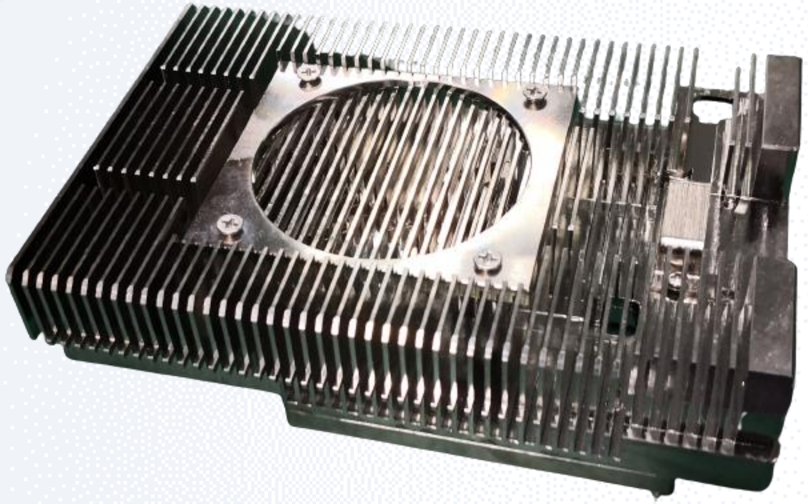
Model No	Custom Cooler
Features	Aluminum extrusion processing technology is adopted; The surface anode is black, and the heat dissipation performance is stable; Spring screw installation, easy and reliable installation; It is used in low-power board chip cooling solutions.
Technical parameters	Scope of application: Customer's own board chip **(TDP 45W)** Dissipator: Aluminum extruded AL6063 machined anode black Product size: 115x78x12.5mm Weight: 132g Service life: more than 50000 hours Accessories: T725 thermally conductive adhesive spring screws are pasted on the bottom surface

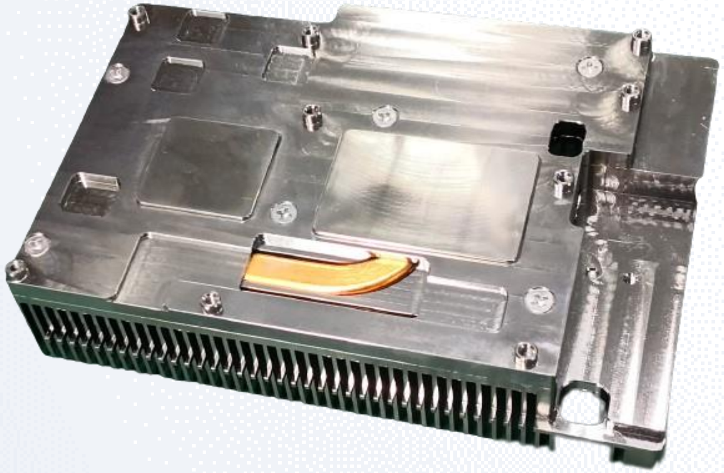
Heatsink



Model No	Custom Cooler
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with a high-efficiency heat pipe to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; It is used as a passive-based solution for professional boards.
Technical parameters	Applicable power consumption: customer's own board chip Product weight: 419g Heat dissipator: aluminum plate + aluminum FIN+ heat pipe Material: AL6063+AL1050+CU1020 Product size: 145x104x29mm

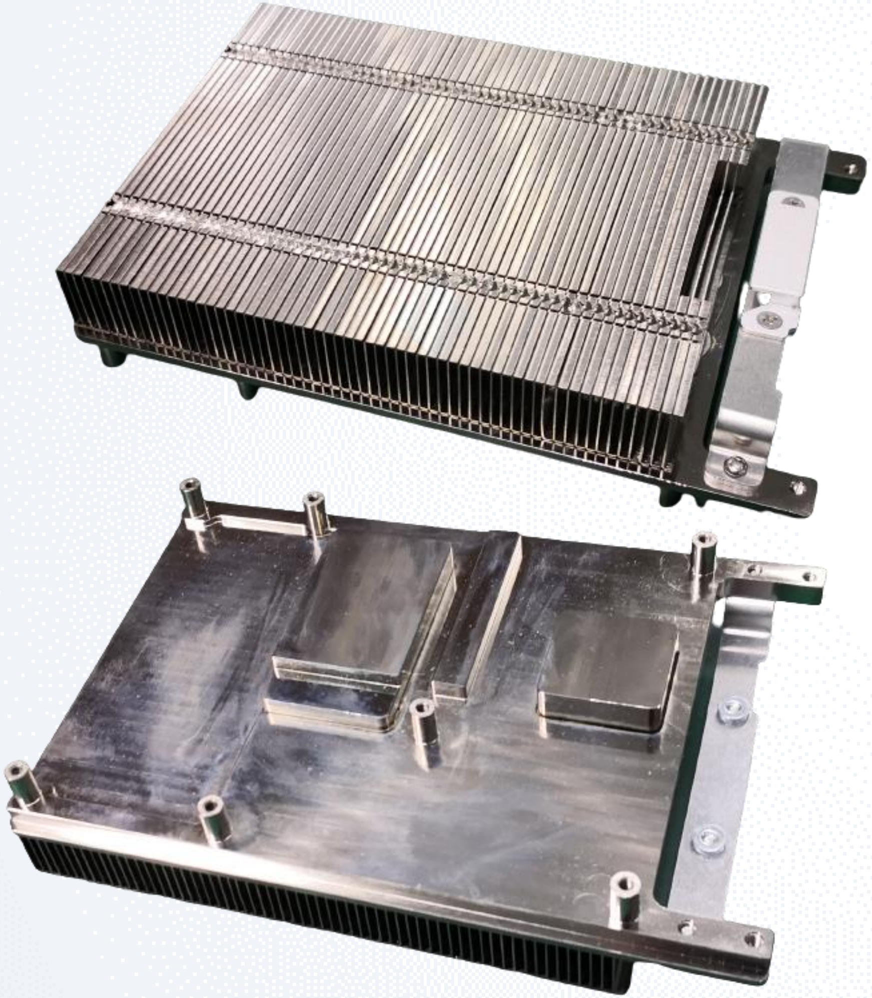
Heatsink





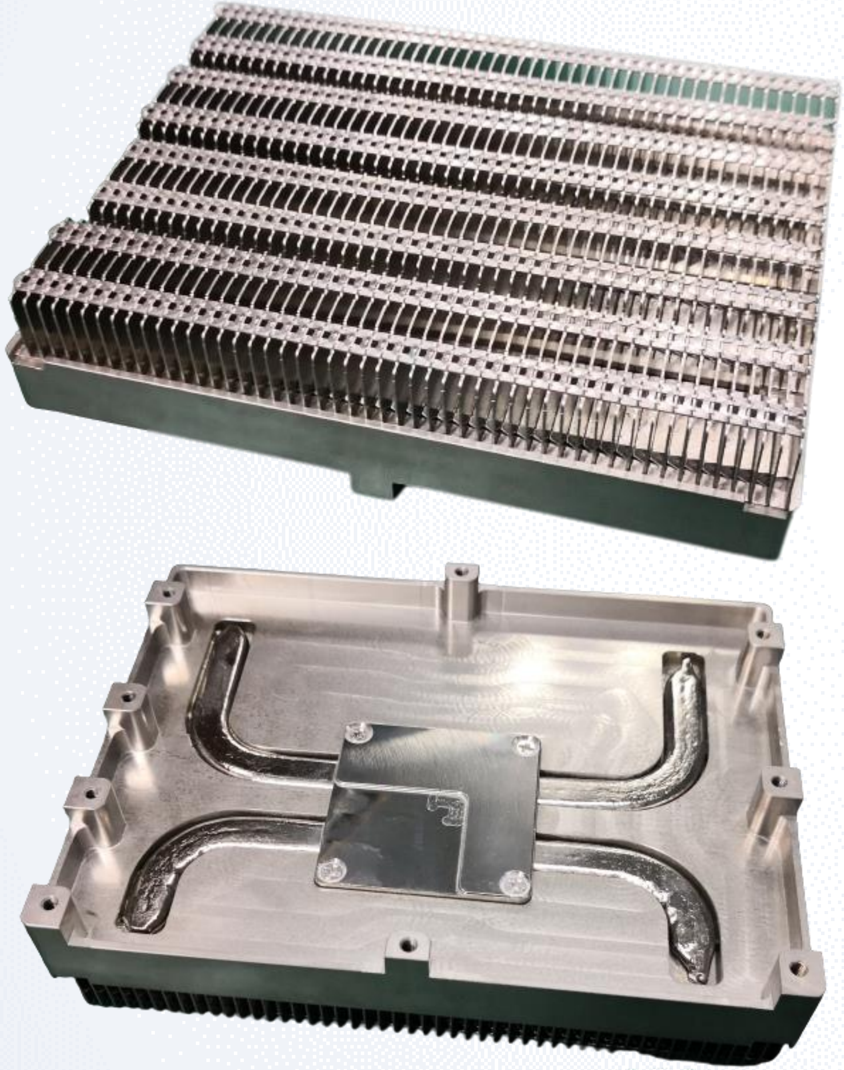
Model No	Custom Cooler
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with a high-efficiency heat pipe to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; It is used as a passive-based solution for professional boards.
Technical parameters	Applicable power consumption: customer's own board chip Product weight: 556g Heat dissipator: aluminum plate + aluminum FIN+ heat pipe Material: AL6063+AL1050+CU1020 Product size: 139x109.5x34mm

Heatsink



Model No	Custom Cooler
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with a high-efficiency heat pipe to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; It is used as a passive-based solution for professional boards.
Technical parameters	Applicable power consumption: customer's own board chip Product weight: 433g Heat dissipator: aluminum plate + aluminum FIN+ heat pipe Material: AL6063+AL1050+CU1020 Product size: 145x104x29mm

Heatsink



Model No	Custom Cooler
Features	Precision stamping buckle FIN processing technology; The copper base plate is equipped with a high-efficiency heat pipe to improve the thermal conductivity efficiency; High-density aluminum heat dissipation fins to increase the heat dissipation area; Special screw installation, convenient, stable and reliable; It is used as a passive-based solution for professional boards.
Technical parameters	Applicable power consumption: customer's own board chip Product weight: 276g Heat dissipator: aluminum plate + aluminum FIN+ heat pipe Material: AL6063+AL1050+CU1020 Product size: 124.5x94x34.5mm

About Everflow

Customization Orientation

Integrity、Pragmatic

HQ in Taipei:

Everflow Technology Co., Ltd
(5F., No.2, Ln.106,No. 102, Wugong 3rd Rd., Wugu Dist., New Taipei City, Taiwan(R.O.C))

Factory in CH：

Everflow Precision Electronic (DongGuan) Co., LTD
Dongguan HanShuo Plastic Co,. Ltd
(Gekeng Yanjiang Industrial Zone, Heng Li Town,Dong Guan City, Guang Dong, China)

COMPANY PROFILE

Everflow Technology Co., Ltd(Abbreviation: EF) :

Established in Dongguan in 1999, is a Taiwan-funded enterprise integrating R&D, production, sales and providing professional cooling fans and thermal modules. The products include cooling fans, thermal modules, and water-cooling systems etc.EF headquartered in Taipei, has numerous manufacturing locations in Dongguan and Xiamen, and has sales outlets and offices in North China, South China, and Southwest China; EF has passed ISO9001, ISO14001 and IATF16949 management system certification, and products are sold to international markets in Europe, America, Asia, etc.

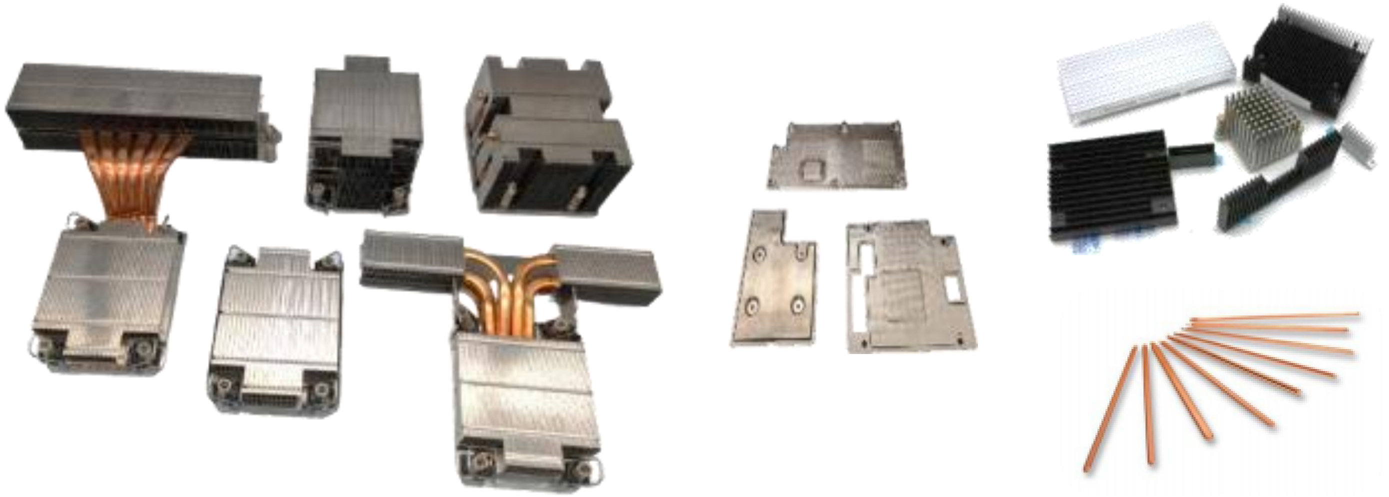
Product Portfolio

Heat Sinks

- Extrusion
- Die Casting
- Forging
- Stacked Fin
- Skived Fin

Cooling Modules

- Heat Pipe Cooling Modules
- Vapor Chamber Cooling Modules
- Thermosiphon
- Cold Plate For Liquid Cooling



Mechanical Parts

Stiffener/ Bolster / Back Plate

Cosmetic Components

Various decorative panels / strips
Media Player / Monitors shells
Handles

Air Cooling
Popular Thermal Cooling Solution

CPU

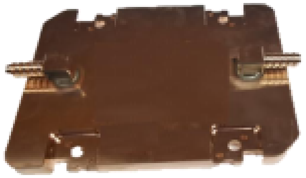
GPU

Base Station

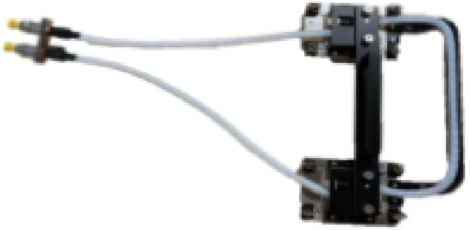
Edge

Switch

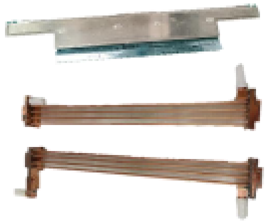
Liquid Cooling Cold Plate
Excellent Thermal Dissipation Solution



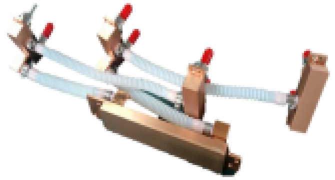
CPU / GPU



Cold Plate Assembly
For System Solution



DIMM / OCP



PSU/ SSD

Technical Support

O New material & technology development

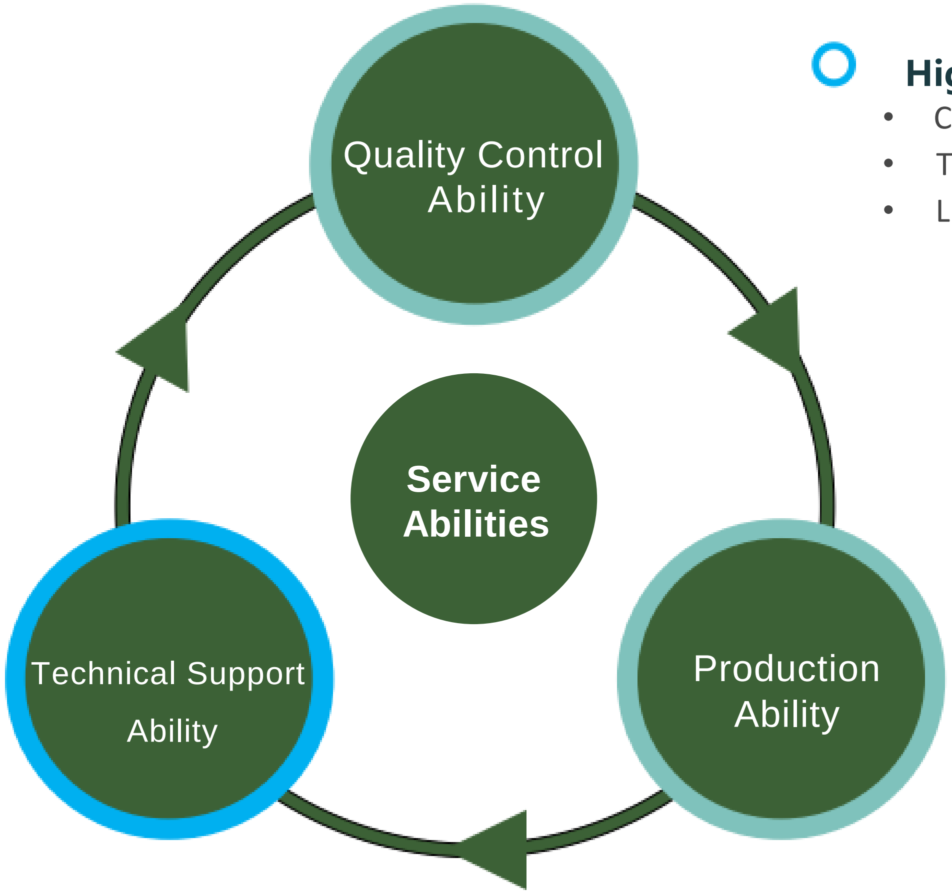
- VC Lid study
- 3D VC solution study with VC+HP and VC+VC.
- Immersion Cooling solution study

O High power solution study

- Composite Design
- Thermosiphon
- Liquid Cooling

O Cooling module design ability

- HP and VC fine tune ability
- Thermal module design and simulation ability



Quality Control Ability

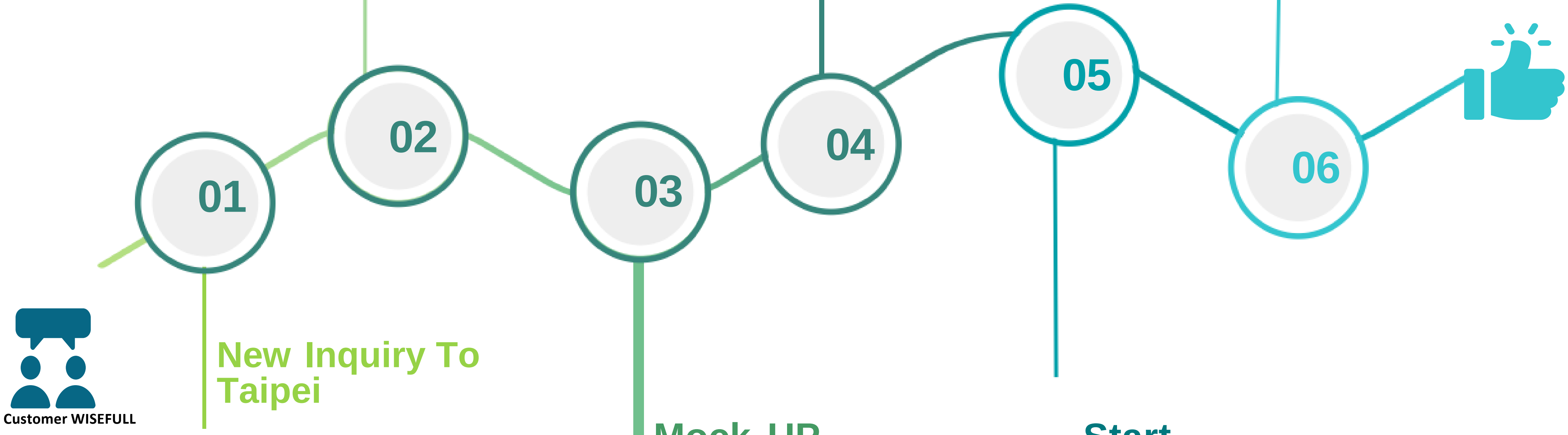
Service Abilities

Production Ability

Technical Support Ability

Heat pipe			Vapor Chamber
D4/D5/D6/D8/D10	Diameter (mm)	Length (mm)	380
60~600	Length (mm)	Width (mm)	380
0.4 ≦ T	Thickness (mm)		T ≧ 2.7
Mesh/Powder/Composite	Wick Structure		Mesh/Powder/Composite
5 ~ 80	Qmax of Component (W/unit)		150 ~ 1000

Project Develop Process Flow



New Inquiry To Taipei

- 2D 3D RFQ
- Design Proposal request

Evaluation

- Quotation
- Design and Simulation Proposal

Mock UP Sample

Design Finalized

- Final 2D and 3D design confirmed.

Start Tooling

NPI and MP

Production Ability

Tooling Dev.

- Extrusion
- Die casting
- Stamping
- Forging
- Fixture / Jig
- Automation

Mechanical Processes

- Cutting
- Stamping
- Bending
- Drilling/ Tapping
- CNC/ Lathe
- Diamond Cutting
- Friction Stir Welding
- Diffusion Welding
- Laser Welding
- Sintering

Inspection

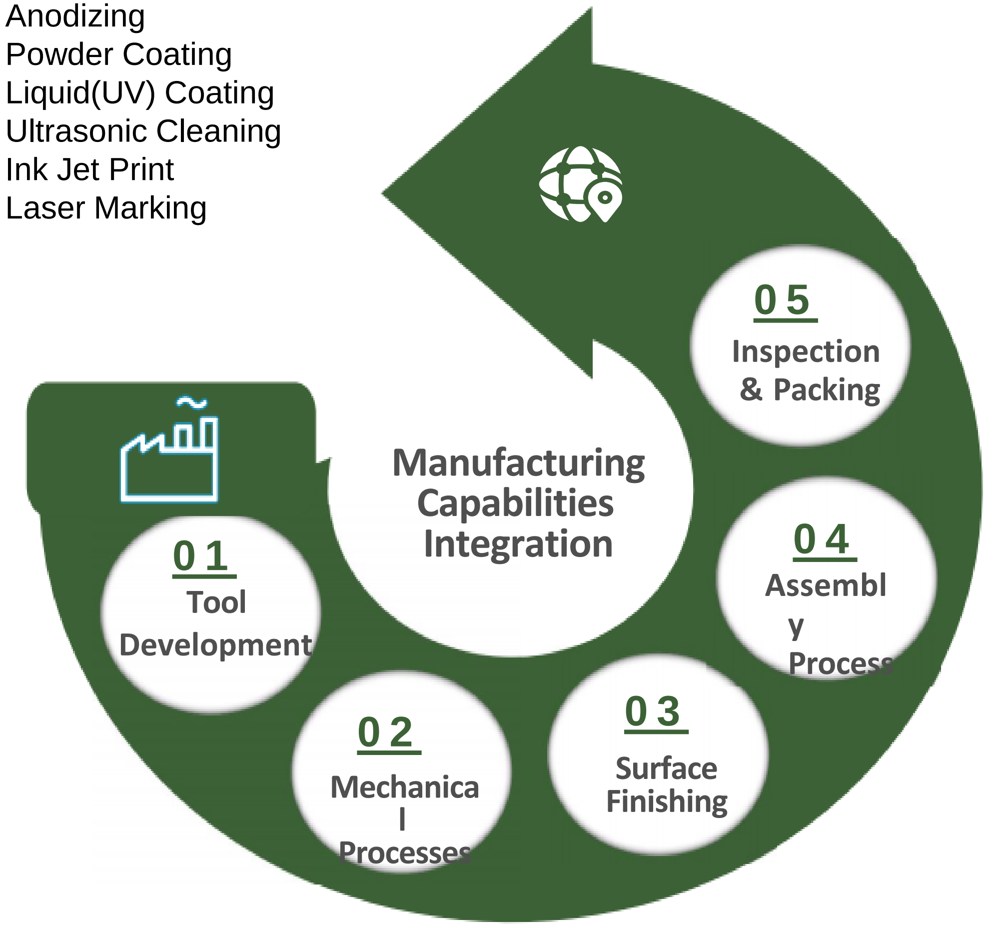
- Thermal Test
- Leakage Test
- Mechanical Check
- Packaging

Surface Finishing

- Chromate Conversion Coating
- Brushing/ Polishing
- Bead Blasting
- Silkscreen/ Pad print
- Anodizing
- Powder Coating
- Liquid(UV) Coating
- Ultrasonic Cleaning
- Ink Jet Print
- Laser Marking

Assembly

- Module Soldering
- Cold Plate Brazing
- Mechanical Assembly



Manufacturing Capabilities Integration

01
Tool Development

02
Mechanical Processes

03
Surface Finishing

04
Assembly Process

05
Inspection & Packing

Soldering & Brazing Ability


Reflow Machine


Diffusion Bonding Furnace


Diffusion Bonding Continuous Furnace


Vacuum Brazing


Continuous Furnace Brazing


Friction Stir Welding

√ Soldering

- Thermal Module
- Heat Pipe Module
- Vapor Chamber Module

√ Diffusion Bonding

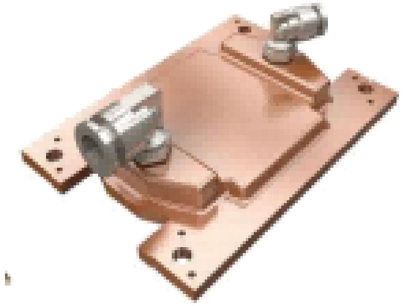
- Vapor Chamber

√ Brazing

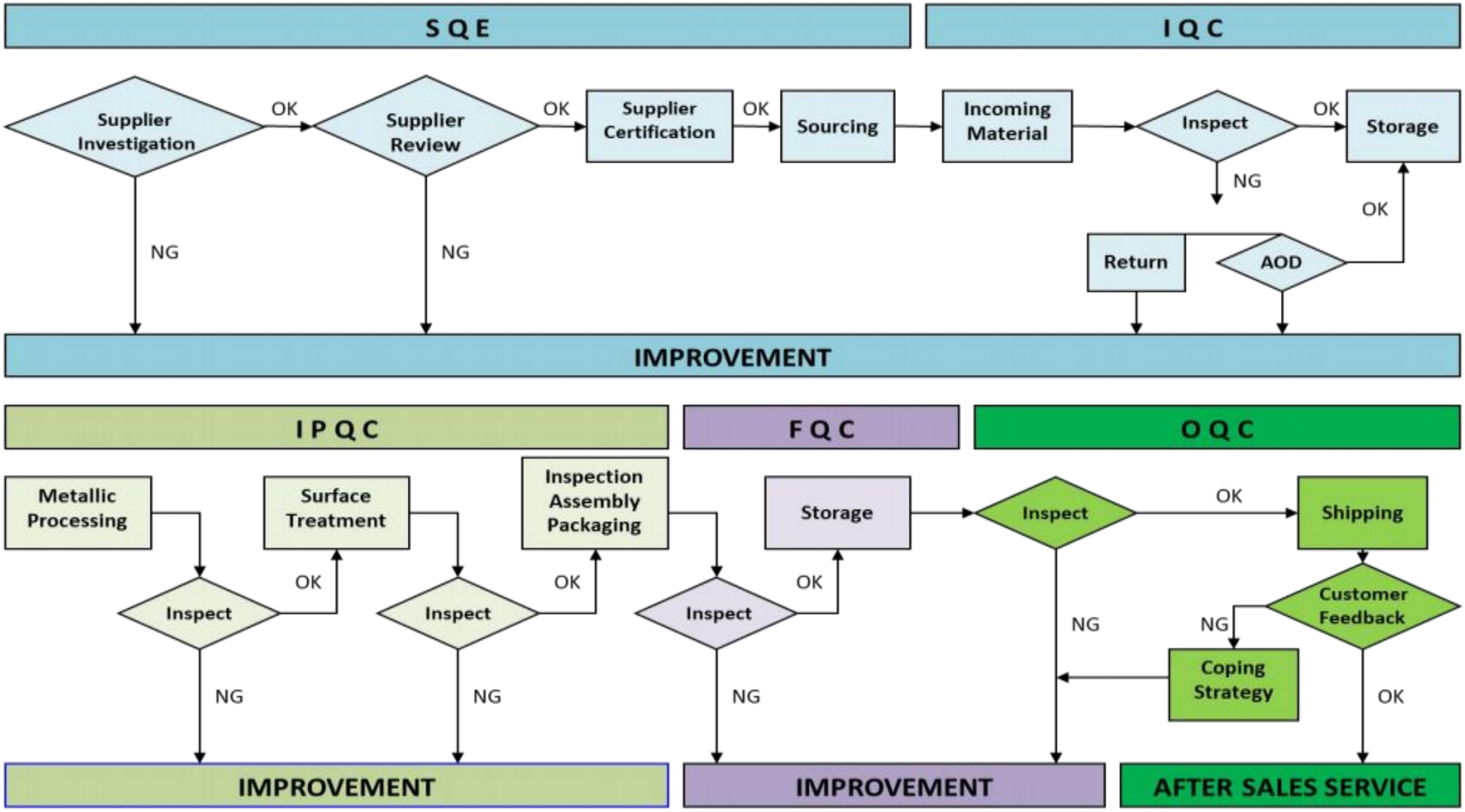
- Cold Plate
- Thermosyphon
- 3D VC

√ FSW

- Cold Plate



Quality System



S Q E

I Q C

Supplier Investigation

OK

Supplier Review

OK

Supplier Certification

OK

Sourcing

Incoming Material

Inspect

OK

Storage

NG

NG

NG

OK

Return

AOD

IMPROVEMENT

I P Q C

F Q C

O Q C

Metallic Processing

Surface Treatment

Inspection Assembly Packaging

Storage

Inspect

OK

Shipping

OK

Inspect

OK

Inspect

OK

Inspect

Customer Feedback

NG

NG

Coping Strategy

NG

NG

NG

OK

IMPROVEMENT

IMPROVEMENT

AFTER SALES SERVICE

Quality Control

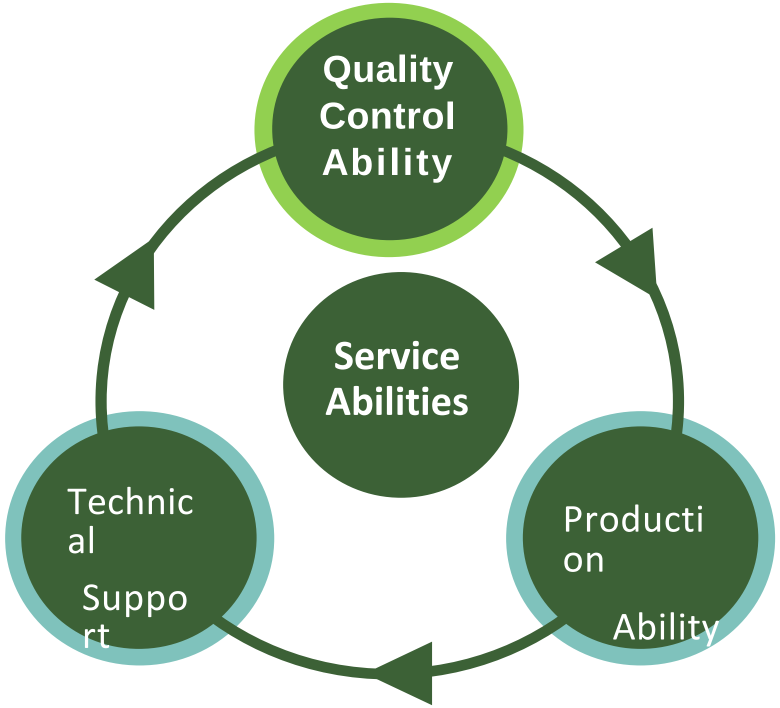
- **Test & Inspection Equipment In House**

  Necessary test equipment and inspection equipment are in house.

- **Heat Pipe & Vapor Chamber Inspection**
  - Burn-In : 100 %
  - Thermal Performance : 100 %
  - Critical Dimension Check : 100 %
  - Appearance Check : 100%

- **Heat Sink & Cooling Module Inspection**
  - Appearance Check : 100 %
  - Critical Dimension Check : 100 %
  - Thermal Test for cooling module: 100 %

- **Cold Plate Inspection**
  - Leakage Test : 100 %
  - Pressure Drop Test : 100 %
  - Critical Dimension Check : 100 %
  - Appearance Check


Quality Control Ability

Service Abilities

Technical Support

Production Ability

Managementsystem

IATF 16949

ISO 9001

ISO 14001

ISO ISO 14064

OHSAS 18001:2007

IECQ QC 080000

Inspection equipment

Dimension Inspection

CMM Image Dimension Measurement System

Automatic Laser Scan Measurement

Image Dimension

Measurement System

3D Scanner

Optical Comparators

Function Inspection

Ultrasound Flaw Test

Flow Resistance Performance Test

Metallographic Microscope

Pencil Scratch Tester

Spring Tension And Compression Testing

Reliability Inspection

Thermal Shock Test

Salt Spray Testing Chamber

Drop Tester

Simulation Car Transportation Testing

Taber Abrasion Tester

RCA Abrasion Tester

Appearance Inspection

Gloss Meter

Electrical Conductivity Meter

Coating Thickness Meter

Spectrophotometer

Metallographic Grinding Tester

Plating Thickness Gauge

Anodizing Sealing Gauge

Roughness Meter

Micro Magnifier

CCD Visual Inspection

Equipment For Reliability Test

Thermal shock test machine

Constant temperature and humidity testing machine

Accelerated Life Test

Qmax test platforms

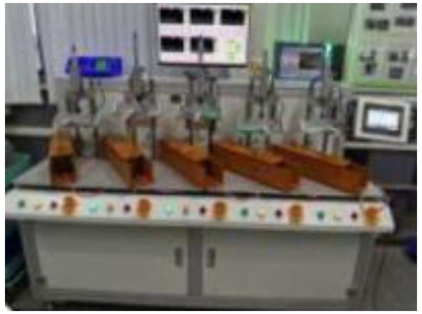
3 D CMM

Salt spraying tester

Leakage Tester

Micro Leakage Test (He Gas)

X-ray spectrum analyzer



Thermal erformance tester

Green Production

EHS Facilities for environment friendly production

- Photovoltaic System
- Water Heating System
- Automatic Anodizing Lines
- Waste water recycling system
- Waste phosphoric acid and sulfuric acid recycling system
- Centralized Aluminum Dust Collection

✓ EHS policy

Obey government environmental law
Continuous improvement on pollution prevention
Clean production and operation
Environmentally sound management
Harmonious development

✓ EHS System

Environmental health & safety management system:
ISO14001 ISO45001

✓ QC080000 HSPM System

Raw Material control
Process control
Finished Products control
X-rays chemical analyze meter

THANKS!